

STRUCTURE: PRODUCT:

Silicon monolithic integrated circuits Stereo Class-D Power Amplifier For Speaker

TYPE: PACKAGE: FEATURES: **BD5431EFS** HTSSOP-A44

- 1) Differential Analog / PWM inputs
- 2) High efficiency and low heat generation eliminates external heat-sinks
- 3) Eliminates pop noise generated when the power supply goes on/off, or when the power supply is suddenly shut off
- 4) High quality muting performance is realized by using the soft-switching technology
- 5) Incorporates a master/slave function that enables synchronous operation when several units are used simultaneously
- Allows the internal PWM sampling clock frequency to be adjusted 6)

OAbsolute maximum ratings (Ta=25°C)

Item	Symbol	Limit	Unit	Conditions
Supply voltage	Vcc	+20	v	Pin7、8、15、16、29、30、37、38、40 ※1 ※2
Power dissipation	Pd	2.0	w	※ 3
		4.5	w	※ 4
Input voltage for signal pin	V _{IN}	-0.2 ~ +7.2	V	Pin1, 2, 3, 4 ※1
Input voltage for control pin	V _{cont}	-0.2 ~ Vcc+0.2	V	Pin20、24 ※1
Input voltage for clock pin	V _{osc}	-0.2 ~ +7.2	V	Pin23 ※1
Operating temperature range	Topr	-40 ~ +85	°C	
Storage temperature range	Tstg	-55 ~ +150	°C	
Maximum junction temperature	Tjmax	+150	°C	

*1 The voltage that can be applied, based on GND(Pin11, 12, 33, 34, 43)
*2 Do not, however exceed Pd and Tjmax=150°C.
*3 70mm × 70mm × 1.6mm, FR4, 1-layer glass epoxy board (Copper on bottom layer 0%) Derating in done at 16mW/°C for operating above Ta=25°C. There are thermal vias on the board.
*4 70mm × 70mm × 1.6mm, FR4, 2-layer glass epoxy board (Copper on bottom layer 100%) Derating in done at 36mW/°C for operating above Ta=25°C. There are thermal vias on the board.

OOperating conditions (Ta=25°C)

Item	Symbol	Limit	Unit	Conditions
Supply voltage	Vcc	+10 ~ +16.5	v	Pin7、8、15、16、29、30、37、38、40 ※1
Load impedance	RL	4 ~ 16	Ω	※ 5

Ж5 Do not, however exceed Pd.

× No radiation-proof design

Status this document

This Japanese version of this document is the formal specification. A customer may use this translation version only for reference to help reading the formal version. If there are any differences in translation version of this document, formal version takes priority.



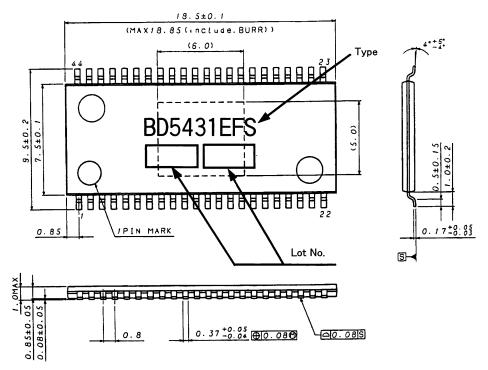
OElectrical characteristics

(Unless otherwise specified Ta=25°C, Vcc=12V, f=1kHz differential analog input、 Rg=0Ω, RL=8Ω, MUTEX=H, MS=L)

Item	Symbol	Limit			11		
		Min	Тур	Max	Unit	Conditions	
Whole circuit							
Circuit current 1 (Sampling mode)	I _{cc1}	-	25	50	mA		
Circuit current 2 (Mute mode)	I _{cc2}	-	10	20	mA	MUTEX=L	
Control circuit							
H level input voltage	VIH	2.3	-	12	V	MUTEX, MS	
L level input voltage	VIL	0	-	0.8	V	MUTEX, MS	
Audio circuit							
Voltage gain	Gv	22	23.5	25	dB	Po=1W, 20log(Vout/Vin)	
Maximum output power 1	P ₀₁	-	10	-	W	R _L =8Ω, THD+n=10% ※1	
Maximum output power 2	Poz	-	17	-	W	R _L =4Ω, THD+n=10% ※ 1	
Total harmonic distortion	THD	1	0.1	-	%	P _o =1W, BW=20Hz~20kHz ※1	
Crosstalk	СТ	60	75	-	dB	P _o =1W, Rg=0Ω, BW=IHF-A	
Output noise voltage (Sampling mode)	V _{NO}	-	60	160	μ Vrms	Rg=0Ω, BW=IHF-A	
Residual noise voltage (Mute mode)	V _{NOM}	-	1	10	μ Vrms	MUTEX=L, Rg=0Ω, BW=IHF-A	
Internal sampling clock frequency	Fosc	180	250	320	kHz		

%1 These items show the typical performance of device and depend on board layout, parts, power supply. The standard value is in mounting device and parts on surface of ROHM's board directly.

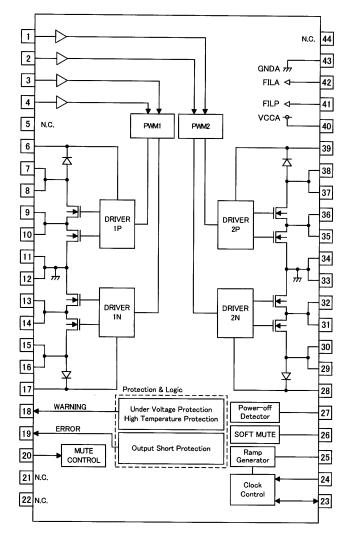
OPackage outline



⁽UNIT: mm) PKG: HTSSOP-A44 Drawing No.: EX195-5002

ROHM

OBlock diagram



OPin	No.	1	Pin	name
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Pin No.			
	Pin name	Pin No.	Pin name
1	IN2N	44	N.C.
2	IN2P	43	GNDA
3	IN1N	42	FILA
4	IN1P	41	FILP
5	N.C.	40	VCCA
6	BSP1P	39	BSP2P
7	VCCP1P	38	VCCP2P
8	VOUFIF	37	VUUPZP
9	OUT1P	36	OUT2P
10	UUTIP	35	UUIZP
11	GNDP1	34	GNDP2
12		33	GINDPZ
13	OUT1N	32	OUT2N
14	00111	31	OUTZN
15	VCCP1N	30	VCCP2N
16	VOOPTIN	29	VUGPZIN
17	BSP1N	28	BSP2N
18	WARNING	27	VHOLD
19	ERROR	26	ТМ
20	MUTEX	25	ROSC
21	N.C.	24	MS
22	N.C.	23	OSC

N.C. : Non Connection.

REV. B



OOperation Notes

(1) Absolute maximum ratings

Use of the IC in excess of absolute maximum ratings such as the applied voltage or operating temperature range may result in IC damage. Assumptions should not be made regarding the state of the IC (short mode or open mode) when such damage is suffered. A physical safety measure such as a fuse should be implemented when use of the IC in a special mode where the absolute maximum ratings may be exceeded is anticipated.

(2) Power supply lines

As return of current regenerated by back EMF of output coil happens, take steps such as putting capacitor between power supply and GND as a electric pathway for the regenerated current. Be sure that there is no problem with each property such as emptied capacity at lower temperature regarding electrolytic capacitor to decide capacity value. If the connected power supply does not have sufficient current absorption capacity, regenerative current will cause the voltage on the power supply line to rise, which combined with the product and its peripheral circuitry may exceed the absolute maximum ratings. It is recommended to implement a physical safety measure such as the insertion of a voltage clamp diode between the power supply and GND pins.

(3) GND potential

Ensure a minimum GND pin potential in all operating conditions.

(4) Setting of heat

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions. This IC exposes its frame of the backside of package. Note that this part is assumed to use after providing heat dissipation treatment to improve heat dissipation efficiency. Try to occupy as wide as possible with heat dissipation pattern not only on the board surface but also the backside.

Class-D power amplifier is High efficiency and low heat generation by comparison with conventional Analog power amplifier. However, In case it is operated continuously by maximum output power, Power dissipation(Pdiss) may exceed package dissipation. Please consider about heat design that Power dissipation(Pdiss) does not exceed Package dissipation(Pd) in average power(Poav). (Tjmax :Maximum junction temperature=150°C, Ta :Peripheral temperature[°C], θ_{ja} :Thermal resistance of package[°C/W], Poav:Average power[W], η :Efficiency)

> Package dissipation: Pd (W) = $(T_{jmax} - T_a) \neq \theta_{ja}$ Power dissipation: Pdiss(W) = Poav * $(1 \neq \eta - 1)$

- (5) Actions in strong magnetic field Use caution when using the IC in the presence of a strong magnetic field as doing so may cause the IC to malfunction.
- (6) Thermal shutdown circuit

This product is provided with a built-in thermal shutdown circuit. When the thermal shoutdown circuit operates, the output transistors are placed under open status. The thermal shutdown circuit is primarily intended to shut down the IC avoiding thermal runaway under abnormal conditions with a chip temperature exceeding Tjmax = 150°C, and is not intended to protect and secure an electrical appliance.

(7) Shorts between pins and misinstallation

When mounting the LSI on a board, pay adequate attention to orientation and placement discrepancies of the LSI. If it is misinstalled and the power is turned on, the LSI may be damaged. It also may be damaged if it is shorted by a foreign substance coming between pins of the LSI or between a pin and a power supply or a pin and a GND.

(8) Power supply on/off

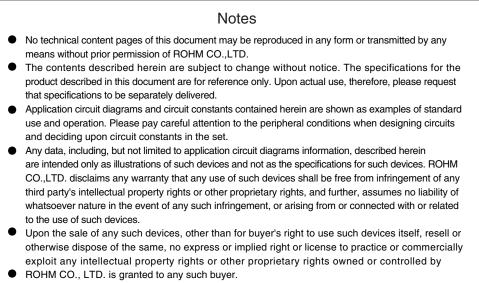
In case power supply is started up, MUTEX(Pin20) always should be set LOW, And in case power supply is shut down, it should be set LOW likewise. Then it is possible to eliminate pop noise when power supply is turned on/off. And also, all power supply terminals should start up and shut down together.

(9) WARNING terminal(Pin18), ERROR terminal(Pin19)

A WARNING flag is outputted when Under Voltage Protection and High Temperature Protection are operated. A Error flag is outputted when Output Short Protection and Output DC Voltage Protection are operated. These flags are the function which the condition of this product is shown in. The use which aimed at the protection except for this product is prohibition.

(10) N.C. terminal(Pin5, 21, 22, 44)

N.C. terminal(Non Connection Pin) does not connect to the inside circuit. Therefore, please open or connect to GND.



• Products listed in this document are no antiradiation design.

The products listed in this document are designed to be used with ordinary electronic equipment or devices (such as audio visual equipment, office-automation equipment, communications devices, electrical appliances and electronic toys).

Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.

It is our top priority to supply products with the utmost quality and reliability. However, there is always a chance of failure due to unexpected factors. Therefore, please take into account the derating characteristics and allow for sufficient safety features, such as extra margin, anti-flammability, and fail-safe measures when designing in order to prevent possible accidents that may result in bodily harm or fire caused by component failure. ROHM cannot be held responsible for any damages arising from the use of the products under conditions out of the range of the specifications or due to non-compliance with the NOTES specified in this catalog.

Thank you for your accessing to ROHM product informations. More detail product informations and catalogs are available, please contact your nearest sales office.

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Appendix1-Rev2.0